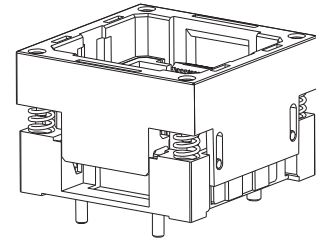


Burn-In Sockets MPS Series

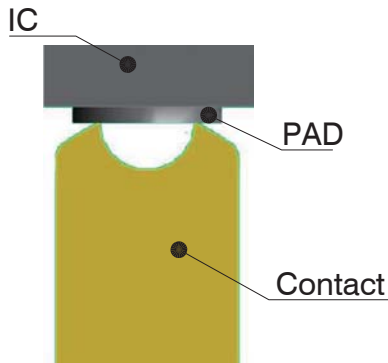
OPEN TOP LGA SOCKET



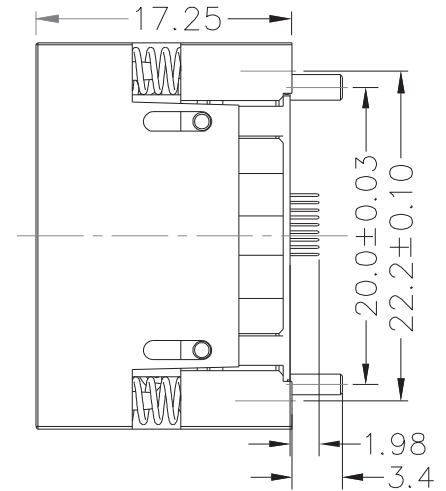
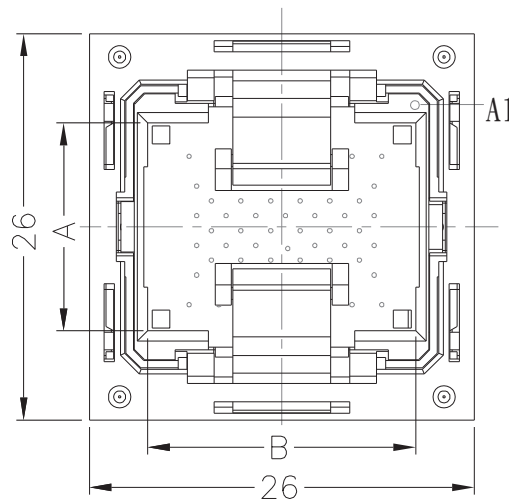
Open Top Style. Accommodates LGA package with 1.0mm pitch.
 Compact size and low actuation force.
 4-Point pinch design for enhanced electrical contact.
 Field exchangeable package location plate.



Please note, we will always request the chip data to ensure we offer a compatible socket.



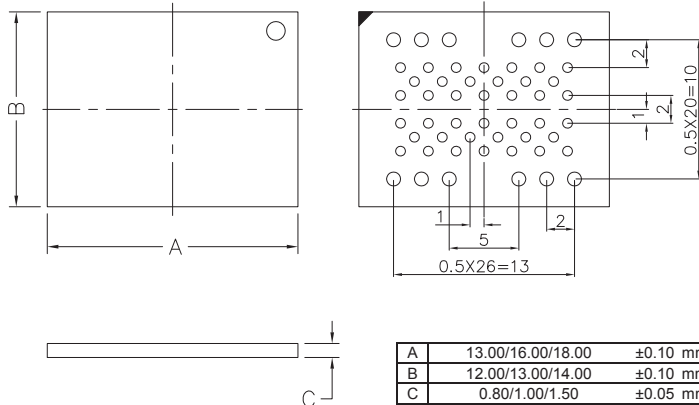
Contact Tip Detail



You may request any specific socket dimension from info@e-tec.com

For top view socket dimension pls. ref. to separate catalog page

Applicable IC



Specifications

Mechanical data

Contact life 25,000 cycles
 Contact Normal Force 3-5g Per Pin
 Operation Force 2.0Kg max.

Material

Insulator (RoHS compliant) PES, PEI
 Contact (RoHS compliant) Beryllium Copper Alloy
 Contact plating Gold cover Nickel

Electrical data

Contact resistance < 30 mΩ
 Current rating 1A
 Insulation resistance at 500V DC 1,000 mΩ

Operating temperature

-55°C to +175°C

Recommendations:

Solder paste – Please use a solder paste w/o any silver!

Solder profile – Please refer to our website www.e-tec.com

E-tec solderless sockets are adapted to a standard PCB thickness of 1.60mm. For a different PCB thickness, please inform E-tec first!

For high pincount SMT sockets, E-tec recommends the use of a pluggable thru-hole socket mounted into a MiniGrid Adapter (see also page 10, 11 & 12 for more details)

For SMT sockets in general, E-tec recommends the use of locating pegs which can be soldered to the PCB for added mechanical strength.

How to order

MPS - xxx - 10 - xx.x/xx

